



Material Content Data Sheet



Sales Product Name				IPD50N03S4L-06		Issued		25. January 2018	
MA#				MA001661994					
Package				PG-TO252-3-11		Weight*		369.52 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.143	0.31	0.31	3092	3092	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		583		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		175		
	non noble metal	copper	7440-50-8	215.017	58.17	58.25	581881	582639	
wire	non noble metal	aluminium	7429-90-5	1.907	0.52	0.52	5160	5160	
encapsulation	organic material	carbon black	1333-86-4	1.268	0.34		3432		
	plastics	epoxy resin	-	22.191	6.01		60052		
	inorganic material	silicondioxide	60676-86-0	103.345	27.97	34.32	279673	343157	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10121	10121	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		246		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	247	
solder	noble metal	silver	7440-22-4	0.033	0.01		90		
	non noble metal	tin	7440-31-5	0.027	0.01		72		
	non noble metal	lead	7439-92-1	1.277	0.35	0.37	3456	3618	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	copper	7440-50-8	19.177	5.19	5.20	51898	51966	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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